

ABSTRACT OF THE DISCLOSURE

A method of fabricating a device using a lithographic process, the method comprising applying a layer of radiation sensitive resist on top of the device, applying a metallic layer on top of the resist layer, and exposing a part of the resist layer to radiation while coupling the metallic layer to a fixed potential so as to apply an electric field across the resist layer, the direction of the electric field being substantially perpendicular to the plane of the resist layer.